



FEATURES

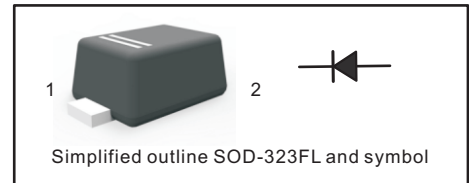
- For surface mounted applications
- Glass Passivated Chip Junction
- Fast reverse recovery time
- Ideal for automated placement
- Lead free in comply with EU RoHS 2011/65/EU directives

MECHANICAL DATA

- Case: SOD-323FL
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 4.5mg / 0.00016oz

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



Absolute Maximum Ratings at 25 °C

Parameter	Symbols	1N4148WSL	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	100	V
Maximum RMS voltage	V_{RMS}	75	V
Continuous Forward Current	I_F	300	mA
Non-reptitive Peak Forward Surge Current at 1ms	I_{FSM}	4	A
Total Power Dissipation	P_{tot}	400	mW
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150	°C

Characteristics at $T_a = 25\text{ °C}$

Parameter	Symbols	1N4148WSL	Units
Reverse Breakdown Voltage at $I_R = 1\mu A$	$V_{(BR)R}$	75	V
Maximum Forward Voltage at 1 mA at 10 mA at 50 mA at 150 mA	V_F	0.715 0.855 1.00 1.25	V
Peak Reverse Current at $V_R = 20V$ $T_j = 25\text{ °C}$ at $V_R = 75V$ $T_j = 25\text{ °C}$ at $V_R = 25V$ $T_j = 150\text{ °C}$ at $V_R = 75V$ $T_j = 150\text{ °C}$	I_R	0.025 1 30 50	μA
Typical Junction Capacitance	C_j	5	pF
Maximum Reverse Recovery Time ⁽¹⁾	t_{rr} Typical	8	ns

(1) Measured with $I_F = 0.5\text{ A}$, $I_R = 1\text{ A}$, $I_{rr} = 0.25\text{ A}$



Fig.1 Forward Current Derating Curve

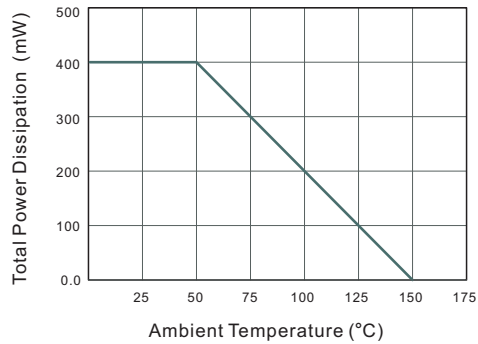


Fig.2 Typical Reverse Characteristics

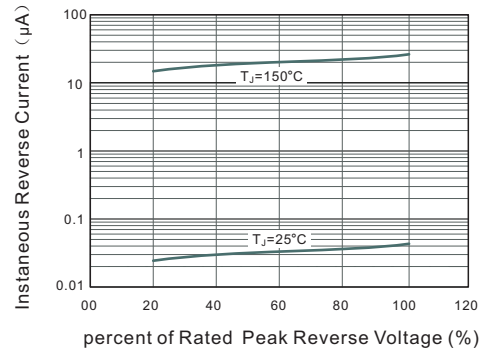


Fig.3 Typical Instaneous Forward Characteristics

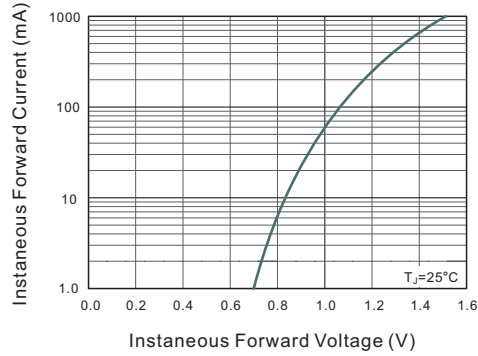
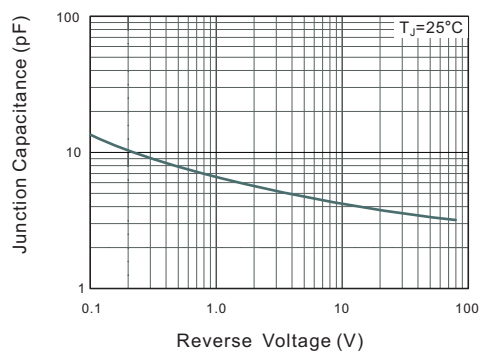


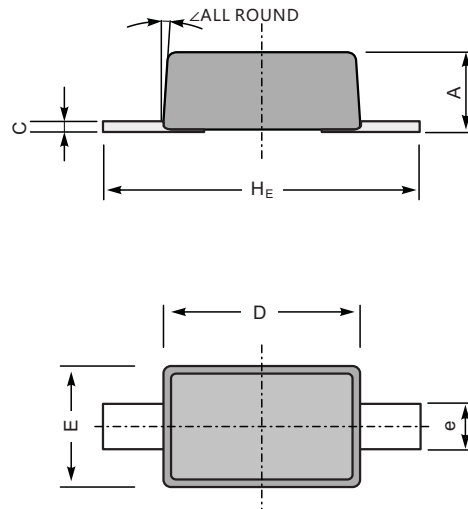
Fig.4 Typical Junction Capacitance



PACKAGE OUTLINE

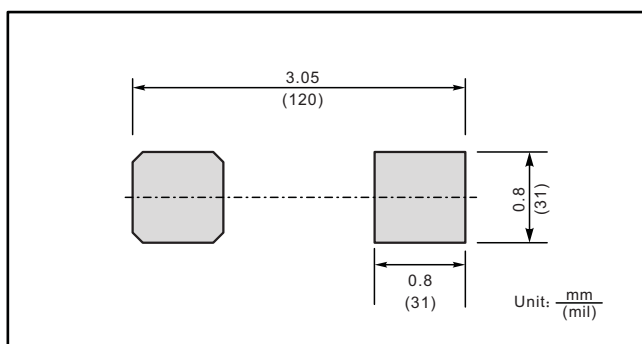
Plastic surface mounted package; 2 leads

SOD-323FL



UNIT		A	C	D	E	e	H _E	∠
mm	max	1.0	0.25	1.8	1.35	0.4	2.7	8°
	min	0.8	0.05	1.6	1.15	0.25	2.3	
mil	max	39	9.8	71	53	18	106	
	min	31	2.0	63	45	10	91	

The recommended mounting pad size



Marking

Type number	Marking code
1N4148WSL	T4